

1-of-10 Decoder

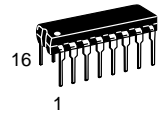
High-Performance Silicon-Gate CMOS

The MC74HC42 is identical in pinout to the LS42. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

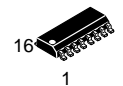
The HC42 decodes a BCD Address to one-of-ten active low outputs. For Address inputs with a hexadecimal equivalent greater than 9, all outputs, Y0–Y9, remain high (inactive).

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2 to 6 V
- Low Input Current: 1 μ A
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard No. 7A
- Chip Complexity: 104 FETs or 26 Equivalent Gates

MC74HC42



N SUFFIX
PLASTIC PACKAGE
CASE 648-08

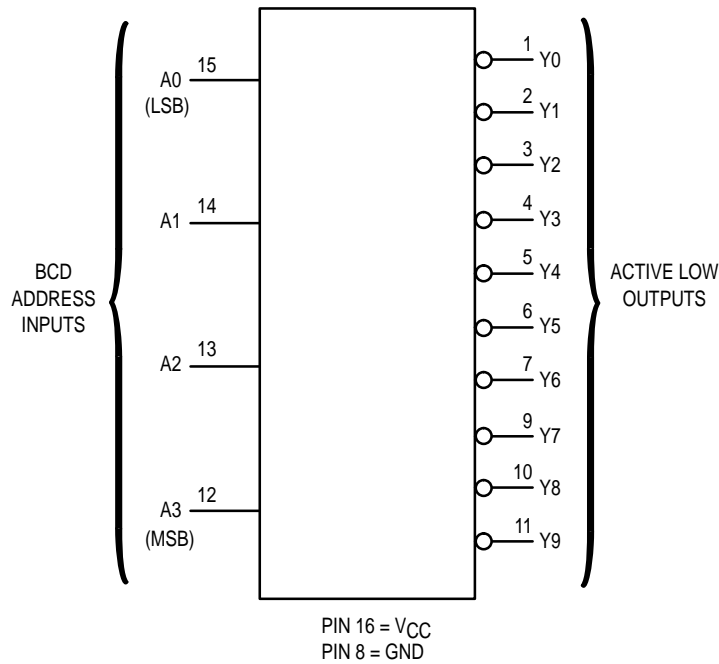


D SUFFIX
SOIC PACKAGE
CASE 751B-05

ORDERING INFORMATION

MC74HCXXN Plastic
MC74HCXXD SOIC

LOGIC DIAGRAM



PIN ASSIGNMENT

Y0	1	16	V _{CC}
Y1	2	15	A0
Y2	3	14	A1
Y3	4	13	A2
Y4	5	12	A3
Y5	6	11	Y9
Y6	7	10	Y8
GND	8	9	Y7



MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit	
V_{CC}	DC Supply Voltage (Referenced to GND)	- 0.5 to + 7.0	V	
V_{in}	DC Input Voltage (Referenced to GND)	- 1.5 to $V_{CC} + 1.5$	V	
V_{out}	DC Output Voltage (Referenced to GND)	- 0.5 to $V_{CC} + 0.5$	V	
I_{in}	DC Input Current, per Pin	± 20	mA	
I_{out}	DC Output Current, per Pin	± 25	mA	
I_{CC}	DC Supply Current, V_{CC} and GND Pins	± 50	mA	
P_D	Power Dissipation in Still Air	Plastic DIP† SOIC Package†	750 500	mW
T_{stg}	Storage Temperature	- 65 to + 150	°C	
T_L	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP or SOIC Package)	260	°C	

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $GND \leq (V_{in} \text{ or } V_{out}) \leq V_{CC}$. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

* Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

† Derating — Plastic DIP: - 10 mW/°C from 65° to 125°C

SOIC Package: - 7 mW/°C from 65° to 125°C

For high frequency or heavy load considerations, see Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit	
V_{CC}	DC Supply Voltage (Referenced to GND)	2.0	6.0	V	
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Referenced to GND)	0	V_{CC}	V	
T_A	Operating Temperature, All Package Types	- 55	+ 125	°C	
t_r, t_f	Input Rise and Fall Time (Figure 1)	$V_{CC} = 2.0 \text{ V}$ $V_{CC} = 4.5 \text{ V}$ $V_{CC} = 6.0 \text{ V}$	0 0 0	1000 500 400	ns

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	V_{CC} V	Guaranteed Limit			Unit
				- 55 to 25°C	$\leq 85^\circ\text{C}$	$\leq 125^\circ\text{C}$	
V_{IH}	Minimum High-Level Input Voltage	$V_{out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out} \leq 20 \mu\text{A}$	2.0	1.5	1.5	1.5	V
			4.5	3.15	3.15	3.15	
			6.0	4.2	4.2	4.2	
V_{IL}	Maximum Low-Level Input Voltage	$V_{out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out} \leq 20 \mu\text{A}$	2.0	0.3	0.3	0.3	V
			4.5	0.9	0.9	0.9	
			6.0	1.2	1.2	1.2	
V_{OH}	Minimum High-Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out} \leq 20 \mu\text{A}$	2.0	1.9	1.9	1.9	V
			4.5	4.4	4.4	4.4	
			6.0	5.9	5.9	5.9	
V_{OL}	Maximum Low-Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out} \leq 20 \mu\text{A}$	2.0	0.1	0.1	0.1	V
			4.5	0.1	0.1	0.1	
			6.0	0.1	0.1	0.1	
I_{in}	Maximum Input Leakage Current	$V_{in} = V_{CC} \text{ or } GND$	6.0	± 0.1	± 1.0	± 1.0	μA
I_{CC}	Maximum Quiescent Supply Current (per Package)	$V_{in} = V_{CC} \text{ or } GND$ $I_{out} = 0 \mu\text{A}$	6.0	8	80	160	μA

NOTE: Information on typical parametric values can be found in Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

AC ELECTRICAL CHARACTERISTICS ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

Symbol	Parameter	V _{CC} V	Guaranteed Limit			Unit
			- 55 to 25°C	≤ 85°C	≤ 125°C	
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Input A to Output Y (Figures 1 and 2)	2.0	150	190	225	ns
		4.5	30	38	45	
		6.0	26	33	38	
t _{TLH} , t _{THL}	Maximum Output Transition Time, Any Output (Figures 1 and 2)	2.0	75	95	110	ns
		4.5	15	19	22	
		6.0	13	16	19	
C _{in}	Maximum Input Capacitance	—	10	10	10	pF

NOTES:

1. For propagation delays with loads other than 50 pF, see Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).
2. Information on typical parametric values can be found in Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

C _{PD}	Power Dissipation Capacitance (Per Package)*	Typical @ 25°C, V _{CC} = 5.0 V	pF
		65	

* Used to determine the no-load dynamic power consumption: $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$. For load considerations, see Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

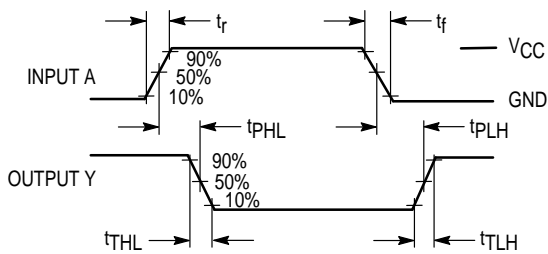
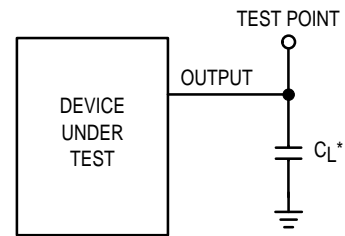


Figure 1. Switching Waveforms



* Includes all probe and jig capacitance

Figure 2. Test Circuit

FUNCTION TABLE

Inputs				Outputs									
A3	A2	A1	A0	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7	Y8	Y9
L	L	L	L	L	H	H	H	H	H	H	H	H	H
L	L	L	H	H	L	H	H	H	H	H	H	H	H
L	L	H	L	H	H	L	H	H	H	H	H	H	H
L	L	H	H	H	H	H	L	H	H	H	H	H	H
L	H	L	L	H	H	H	H	L	H	H	H	H	H
L	H	L	H	H	H	H	H	H	L	H	H	H	H
L	H	H	L	H	H	H	H	H	H	L	H	H	H
L	H	H	H	H	H	H	H	H	H	H	L	H	H
H	L	L	L	H	H	H	H	H	H	H	H	L	H
H	L	L	H	H	H	H	H	H	H	H	H	H	L
H	L	H	L	H	H	H	H	H	H	H	H	H	H
H	L	H	H	H	H	H	H	H	H	H	H	H	H
H	H	L	L	H	H	H	H	H	H	H	H	H	H
H	H	L	H	H	H	H	H	H	H	H	H	H	H
H	H	H	L	H	H	H	H	H	H	H	H	H	H
H	H	H	H	H	H	H	H	H	H	H	H	H	H

PIN DESCRIPTIONS

INPUTS

A0, A1, A2, A3, (Pins 15, 14, 13, 12)

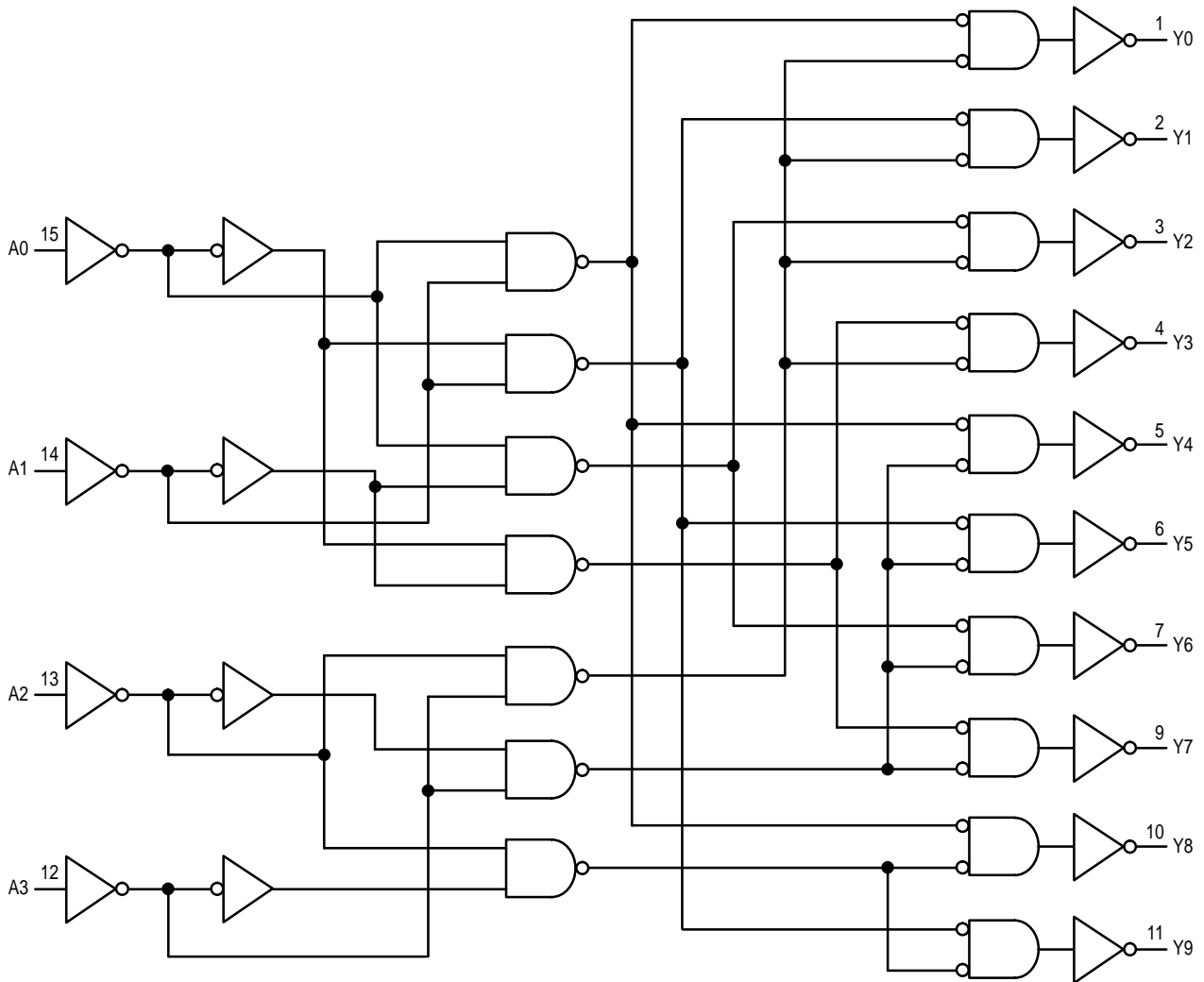
BCD Address Inputs. The BCD address present at these inputs determines which output is active-low. These inputs are arranged such that A3 is the most-significant bit and A0 is the least significant bit. Addresses with a hexadecimal equivalent number greater than nine are not decoded.

OUTPUTS

Y0 – Y9 (Pins 1 – 7, 9 – 11)

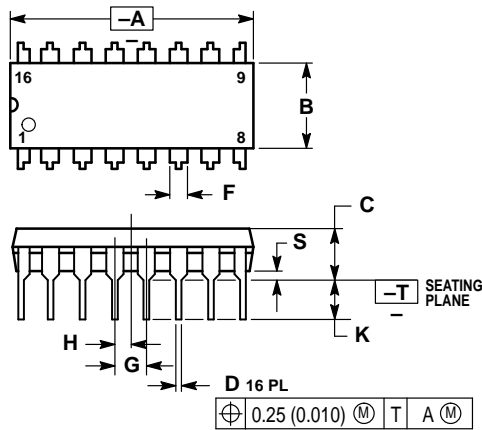
Active-Low Decoded Outputs. These outputs assume a low level when addressed and remain high when not addressed.

EXPANDED LOGIC DIAGRAM



OUTLINE DIMENSIONS

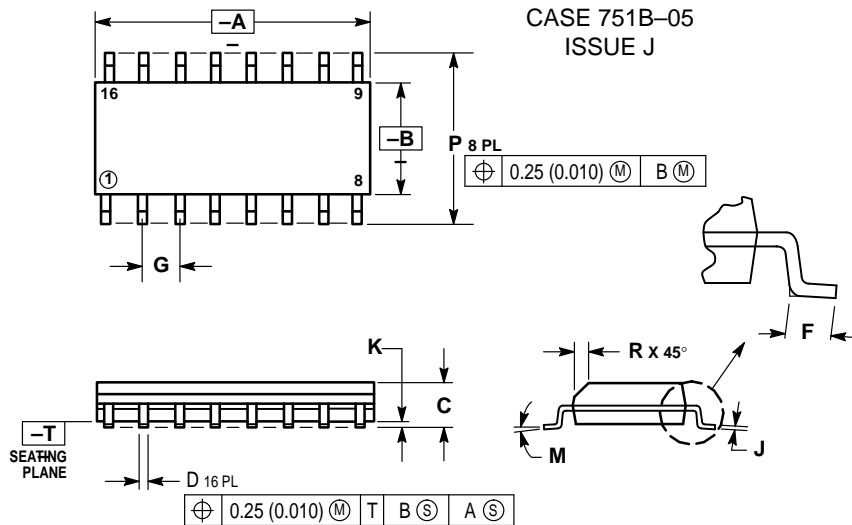
N SUFFIX
PLASTIC PACKAGE
CASE 648-08
ISSUE R



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.070	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

D SUFFIX
PLASTIC SOIC PACKAGE
CASE 751B-05
ISSUE J



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

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